



## Product Change Notification / ASER-06ZMCM207

---

**Date:**

14-Apr-2021

**Product Category:**

Ethernet Switches

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4630 Initial Notice: Qualification of STA as an additional assembly site for selected LAN9303 device family available in 56L VQFN (8x8x0.9mm) package.

**Affected CPNs:**

[ASER-06ZMCM207\\_Affected\\_CPN\\_04142021.pdf](#)

[ASER-06ZMCM207\\_Affected\\_CPN\\_04142021.csv](#)

**Notification Text:**

**PCN Status:**Initial notification.

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**Qualification of STA as an additional assembly site for selected LAN9303 device family available in 56L VQFN (8x8x0.9mm) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change	
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	STATS Chippac Ltd. (STA)
Wire material	PdCu	PdCu	CuPdAu
Die attach material	EN-4900F	EN-4900F	8290

<b>Molding compound material</b>	G631B	G631B	G700E
<b>Lead frame material</b>	C194	C194	C194
<b>Lead frame lead lock</b>	No	No	Yes
	See Pre and Post Change Summary for comparison.		
<b>Lead frame paddle size</b>	240X240 mils	240X240 mils	236X236 mils

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying STA as an additional assembly site

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**August 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	April 2021						August 2021				
Workweek	1 4	1 5	1 6	1 7	1 8	-->	3 2	3 3	3 4	3 5	3 6
Initial PCN Issue Date			X								
Qual Report Availability								X			
Final PCN Issue Date								X			

**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**

**April 14, 2021:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

PCN\_ASER-06ZMCM207\_Pre and Post Change Summary.pdf  
PCN\_ASER-06ZMCM207\_Qual\_Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

# **CCB 4630**

## **Pre and Post Change Summary**

### **PCN #: ASER-06ZMCM207**



---

A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

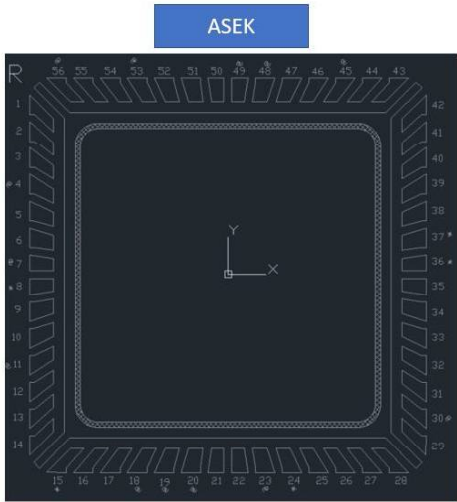
**Qualification of STA as an additional assembly site for selected LAN9303 device family available in 56L VQFN (8x8x0.9mm) package.**



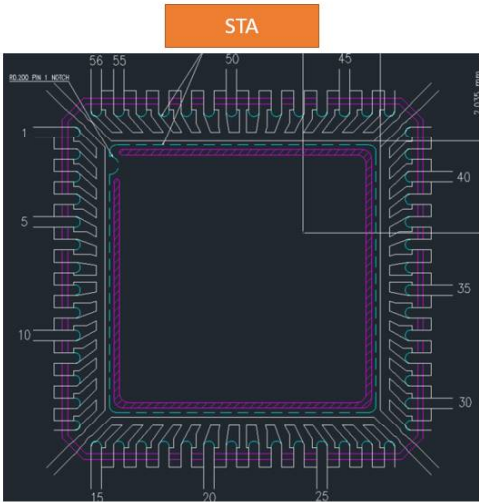
SMART | CONNECTED | SECURE

# Lead frame Comparison

ASE



STA





**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN#: ASER-06ZMCM207**

**Date**

**March 22, 2021**

**Qualification of STA as an additional assembly site for  
selected LAN9303 device family available in 56L VQFN  
(8x8x0.9mm) package.**

Purpose: Qualification of STA as an additional assembly site for selected LAN9303 device family available in 56L VQFN (8x8x0.9mm) package.

CCB No: 4630

<u>Misc.</u>	Assembly site	STA
	MP Code (MPC)	TA3017RTXB0C
	Part Number (CPN)	LAN9303I-ABZJ
	MSL information	MSL-3 @260C
	Assembly Shipping Media (T/R, Tube/Tray)	UBOT Tray (UF08081.01026XB 02)
	Base Quantity Multiple (BQM)	Tray - 260
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	236X236 mils
	Material	C194
	Manufacturer	Samsung
	DAP Surface Prep	Double Ring
	Treatment	Non-Rough
	Process	Etched
	Lead-lock (With Locking Holes)	Yes
	Lead Plating	Matte Sn
	Strip Size	250mmX70 mm
	Strip Density	108 units / strip
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	8290
	Conductive	Yes
<u>MC</u>	Part Number	G700E
<u>PKG</u>	PKG Type	VQFN
	Pin/Ball Count	56L
	PKG width/size	8X8X0.9 mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Standard Pb-free Solderability	J-STD-002D; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MTAI	MTAI	56LVQFN	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0	5	MTAI	MTAI	56LVQFN	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	MTAI	MTAI	56LVQFN	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	MTAI	MTAI	56LVQFN	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	MTAI	56LVQFN	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at at room temp 25°C and hot temp 100°C. MSL3 / 260c	231	15	3	738	0	15	MTAI	MTAI	56LVQFN	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
UHAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at room temp 25°C. Requires 2X Rel stress Testing	77	5	3	246	0	10	MTAI	MTAI	56LVQFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp 100°C; 3gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. Requires 2X Rel stress Testing	77	5	3	246	0	15	MTAI	MTAI	56LVQFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.



ASER-06ZMCM207 - CCB 4630 Initial Notice: Qualification of STA as an additional assembly site for selected LAN

Affected Catalog Part Numbers(CPN)

LAN9303-ABZJ

LAN9303I-ABZJ

LAN9303I-ABZJ-TR